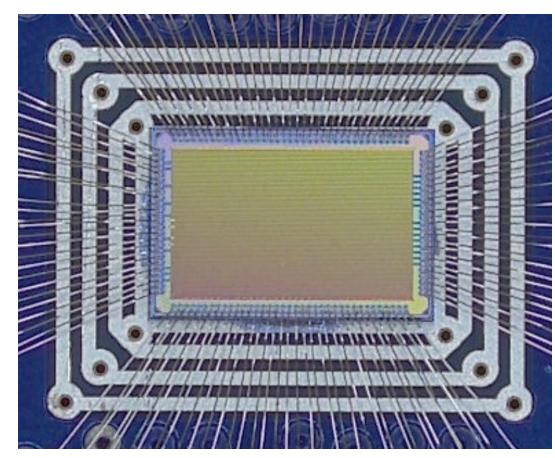
BROOM An open-source out-of-order processor with resilient low-voltage operation in 28nm CMOS



Christopher Celio, Pi-Feng Chiu, Krste Asanović, David Patterson, and Borivoje Nikolic Hot Chips 2018



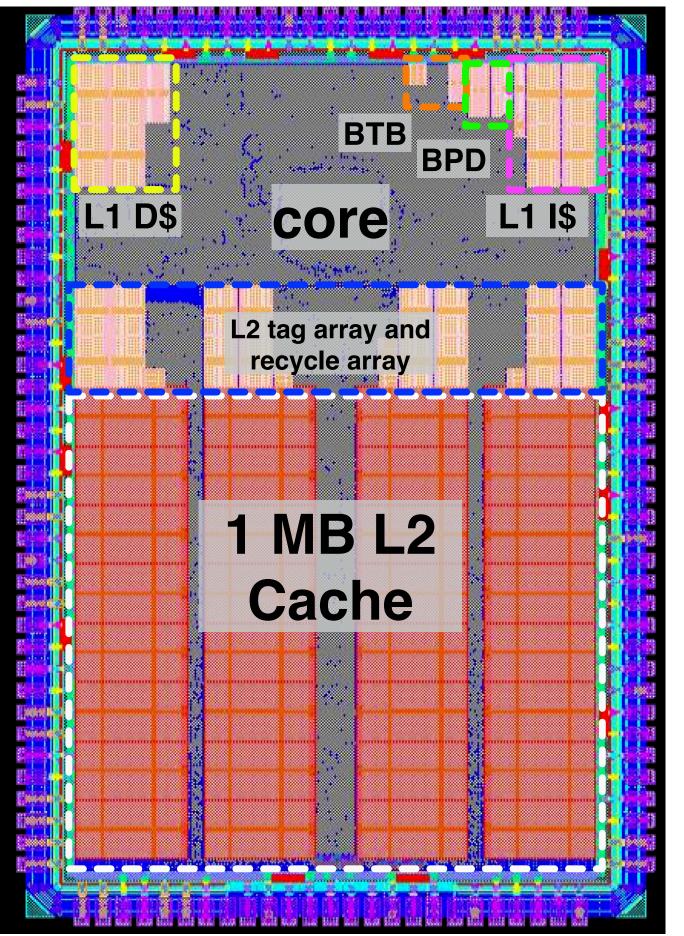
Berkeley Architecture Research





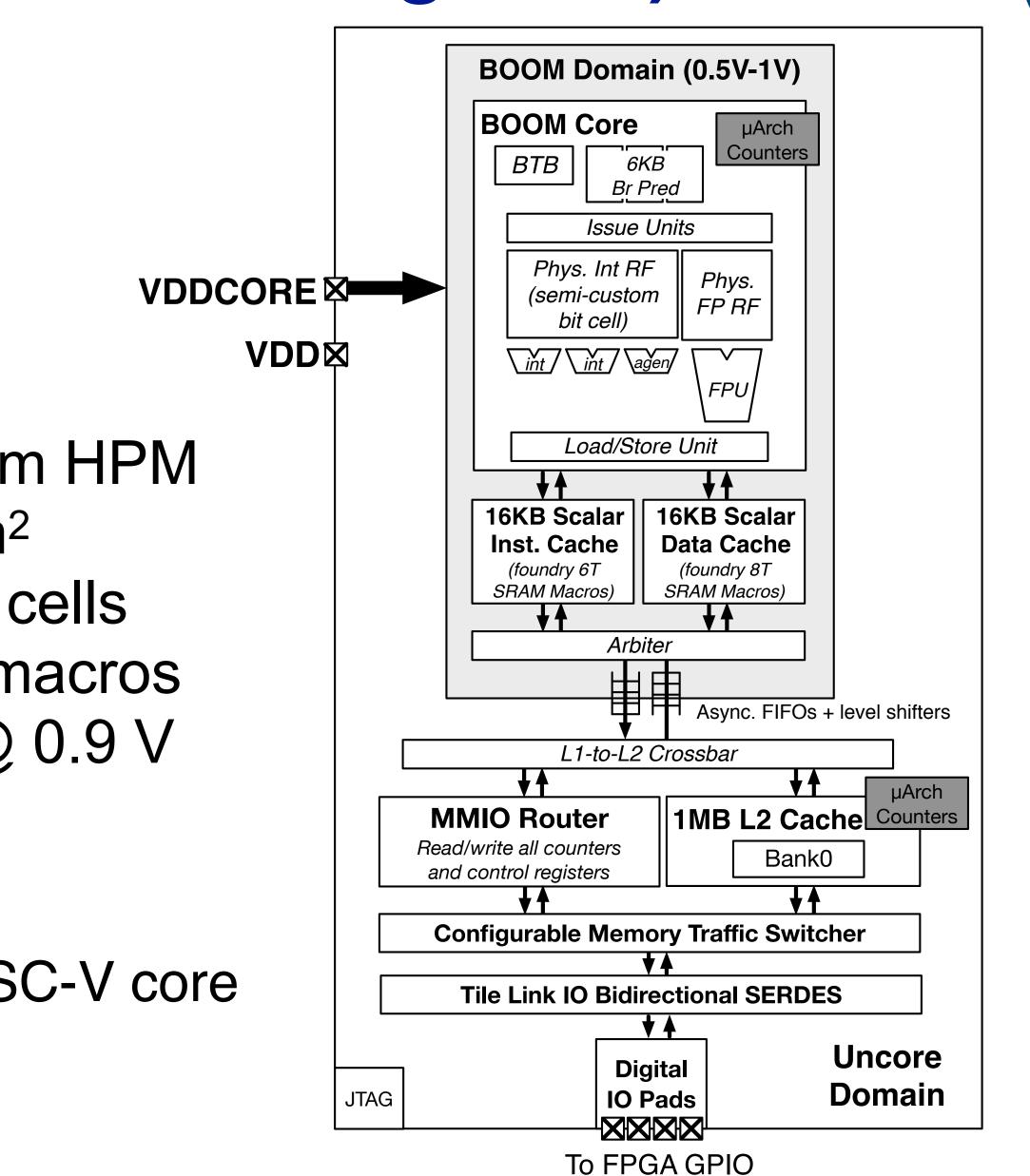
BROOM Chip (Taped out Aug 2017)





TSMC 28 nm HPM 6 mm² 417k std cells 73 SRAM macros 1.0 GHz @ 0.9 V

Open-source superscalar out-of-order RISC-V core
Resilient cache for low-voltage operation











What is BROOM?

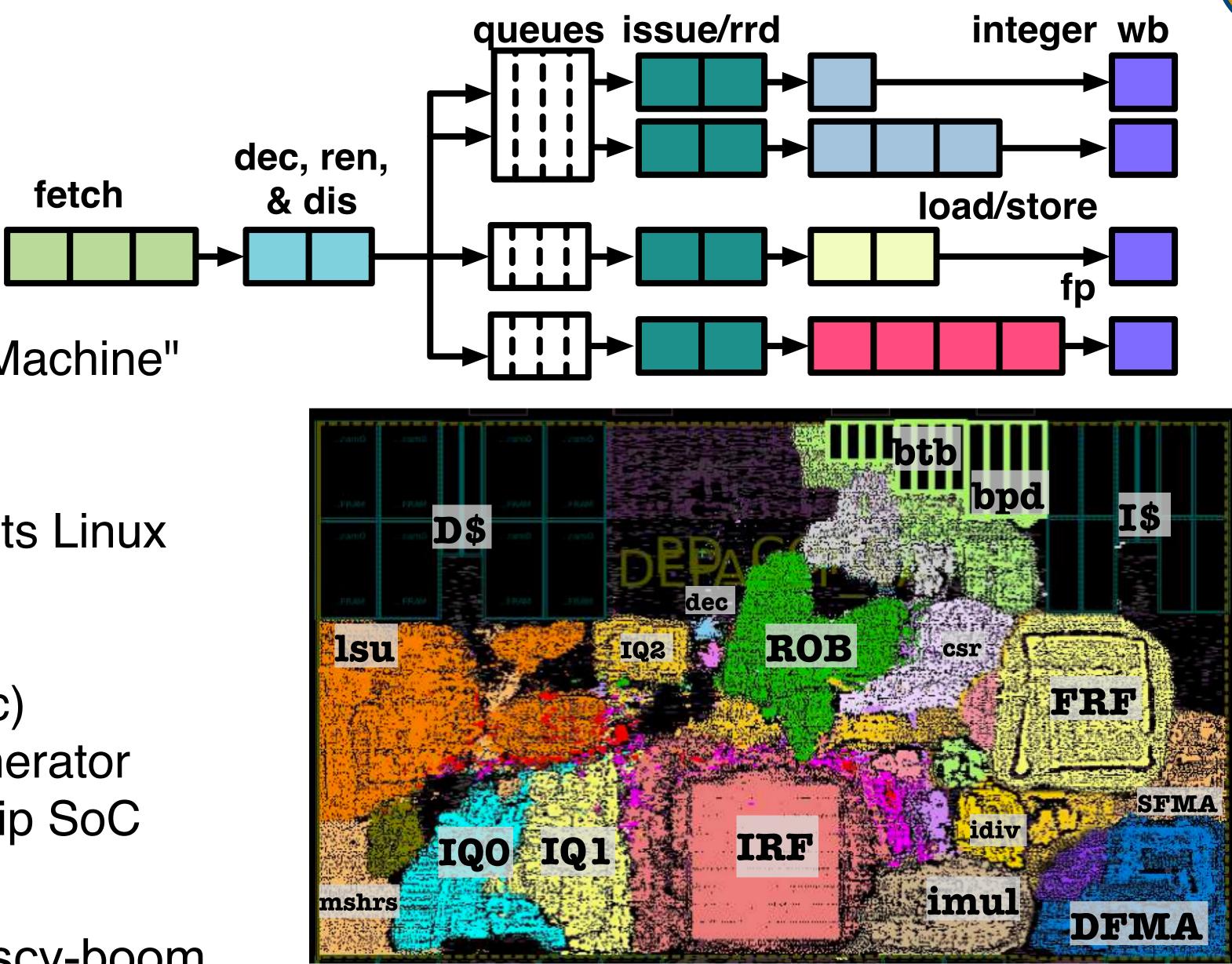
- The RISC-V BOOM Core
- Micro-architectural-level assist techniques
 - Line Disable (LD)
 - Line Recycle (LR)
 - Dynamic Column Redundancy (DCR)
 - Bit Bypass with SRAM (BB-S)
- The Agile Design Experience
- Chip Implementation
- Low Voltage Experimental Results
- Future Directions







What is BOOM?



- Berkeley Out-of-Order Machine"
- out-of-order
- superscalar
- Implements RV64G, boots Linux
- It is synthesizable
- it is open-source
- written in Chisel (16k loc)
- It is parameterizable generator
- built on top of Rocket-chip SoC Ecosystem

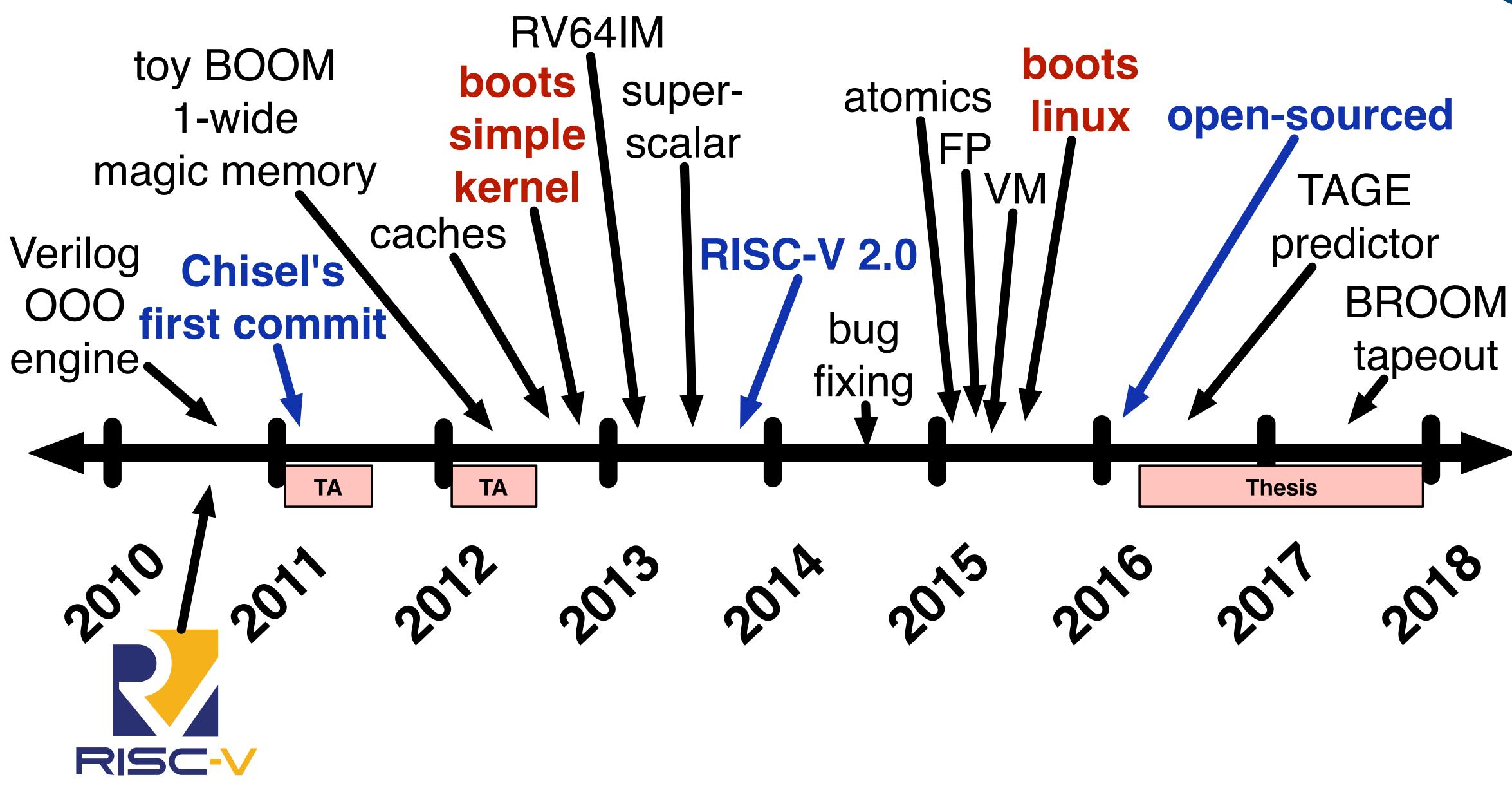
http://ucb-bar.github.io/riscv-boom







Timeline (the path to Hot Chips)

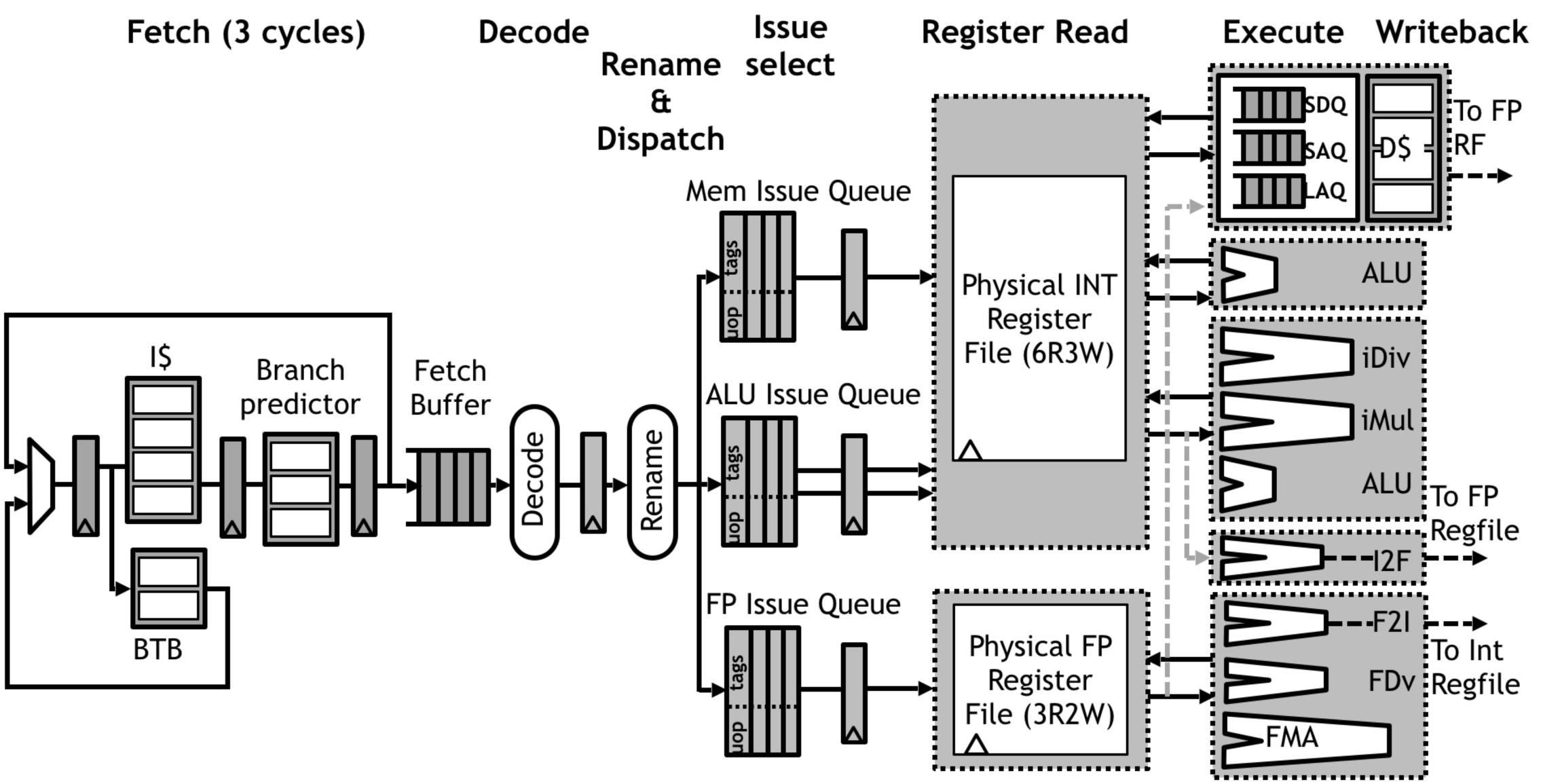












The BOOM Core

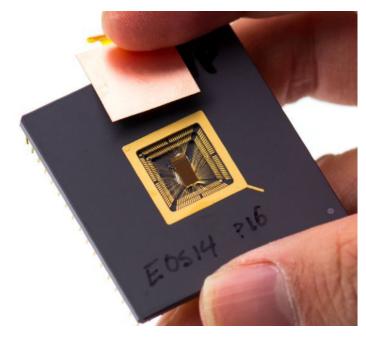


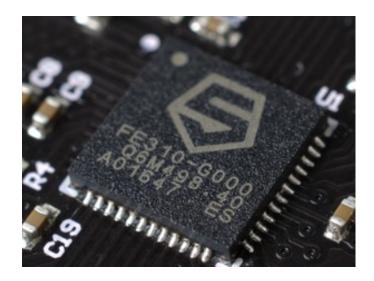






- The Rocket-chip SoC Generator
- Started in 2011
- Taped out 10 (13?) 17 times by Berkeley + many others
- 6,016 commits
- 64 contributors
- Commercial quality
- Replace standard in-order core with BOOM
- Leverage Rocket-chip as a library of processor components

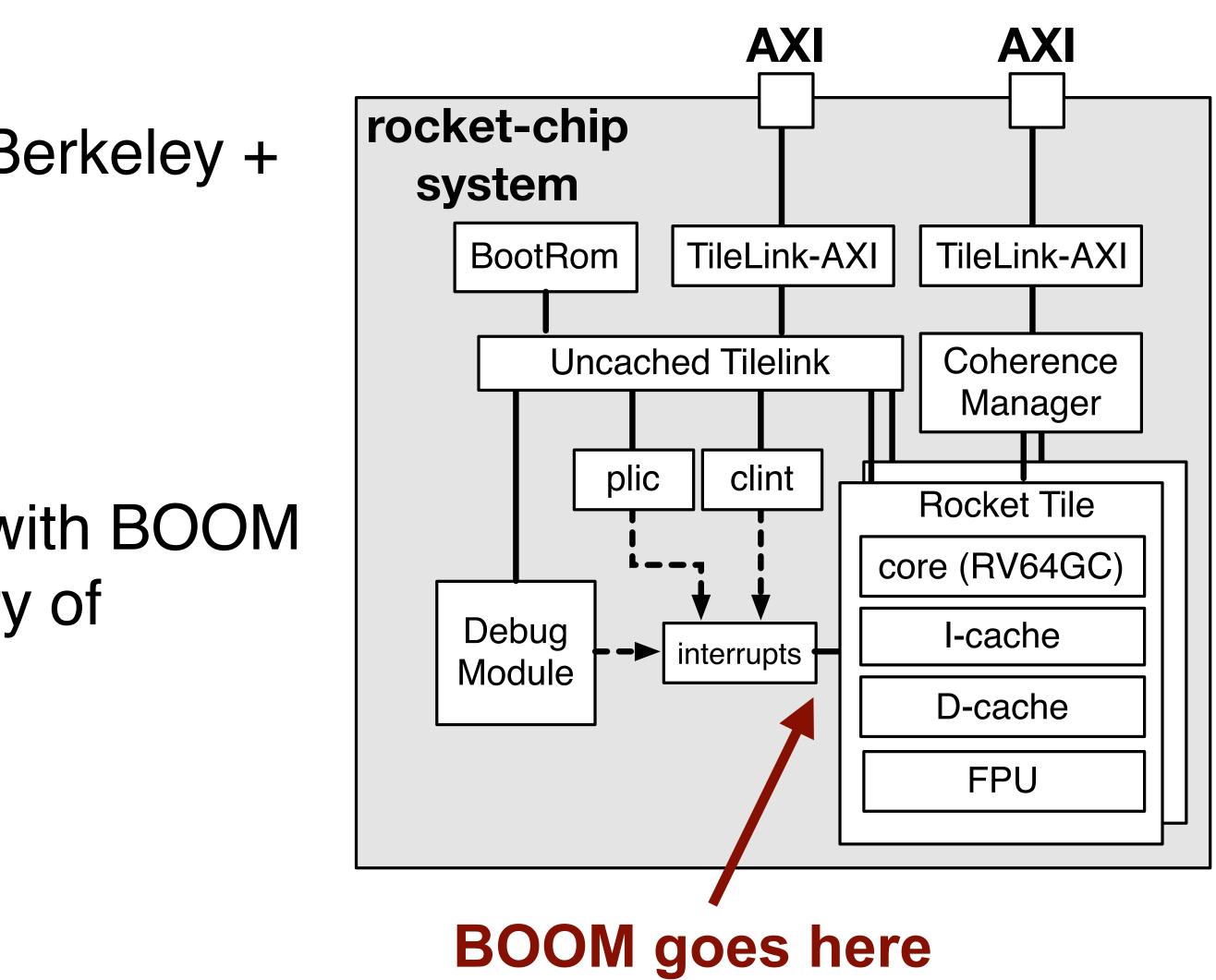




https://github.com/freechipsproject/rocket-chip

Leveraging Open-source RTL









Core Comparison

Processor	SiFive U54 Rocket (RV64GC)	Berkeley BOOMv2 (RV64G)	OpenSPARC T2	ARM Cortex-A9	Intel Xeon Ivy
Language	Chisel	Chisel	Verilog	_	SystemVerilog
Core LoC	8,000	16,000	290,000	_	_
SoC LoC	34,000	50,000	1,300,000	_	_







Core Comparison

Processor	SiFive U54 Rocket (RV64GC)	Berkeley BOOMv2 (RV64G)	OpenSPARC T2	ARM Cortex-A9	Intel Xeon Ivy
Language	Chisel	Chisel	Verilog	_	SystemVerilog
Core LoC	8,000	16,000	290,000	-	_
SoC LoC	34,000	50,000	1,300,000	_	—
Foundry	TSMC	TSMC	ΤI	TSMC	Intel
Technology	28 nm (HPC)	28 nm (HPM)	65 nm	40 nm (G)	22 nm
Core+L1 Area	0.54 mm ²	0.52 mm ² 16kB/16kB	~12 mm ²	~2.5 mm ²	~12 mm ² core+L1+L2
Coremark/MHz	2.75	3.77	1.64*	3.71	5.60
Frequency	1.5 GHz	1.0 GHz	1.17 GHz	1.4 GHz	3.3 GHz

*From <u>eembc.org</u>. 32 threads/8 cores achieve 13 Cm/MHz.

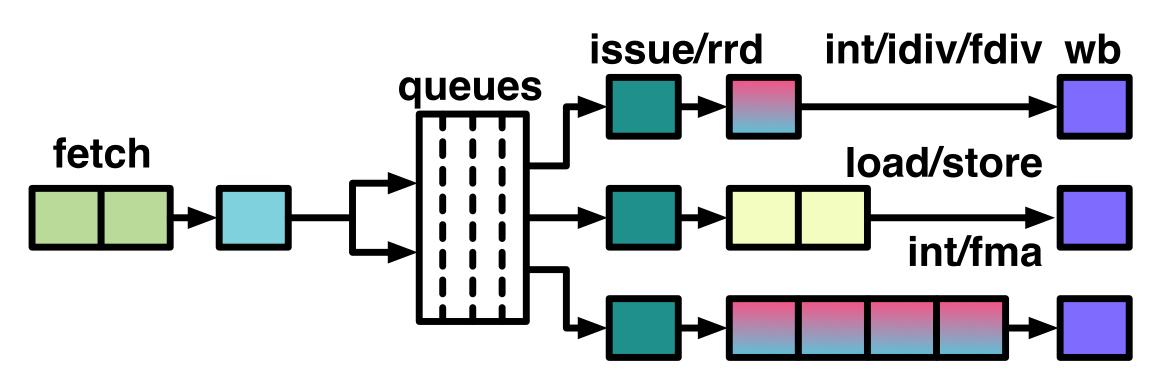




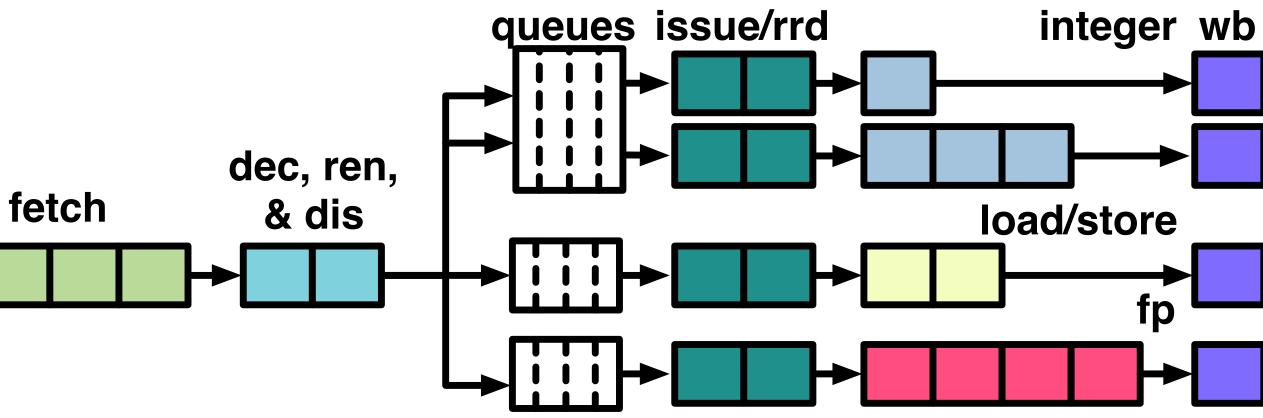


	BOOMv1	BOOMv2
BTB entries	40 (fully-assoc)	64 x 4 (set-assoc)
Fetch Width	2 insts	2 insts
Issue Width	3 micro-ops	4 micro-ops
Issue Entries	20	16/20/10
Regfile	7r3w (unified)	6r3w (inst), 3r2w (fp)
Exe Units	iALU+iMul+FMA iALU+fDiv Load/Store	iALU+iMul+iDiv iALU FMA+fDiv Load/Store

SPIRE UC Berkelev Case study: how agile is the BOOM generator?



BOOM v1 (April 2017)



BOOM v2 (Aug 2017)

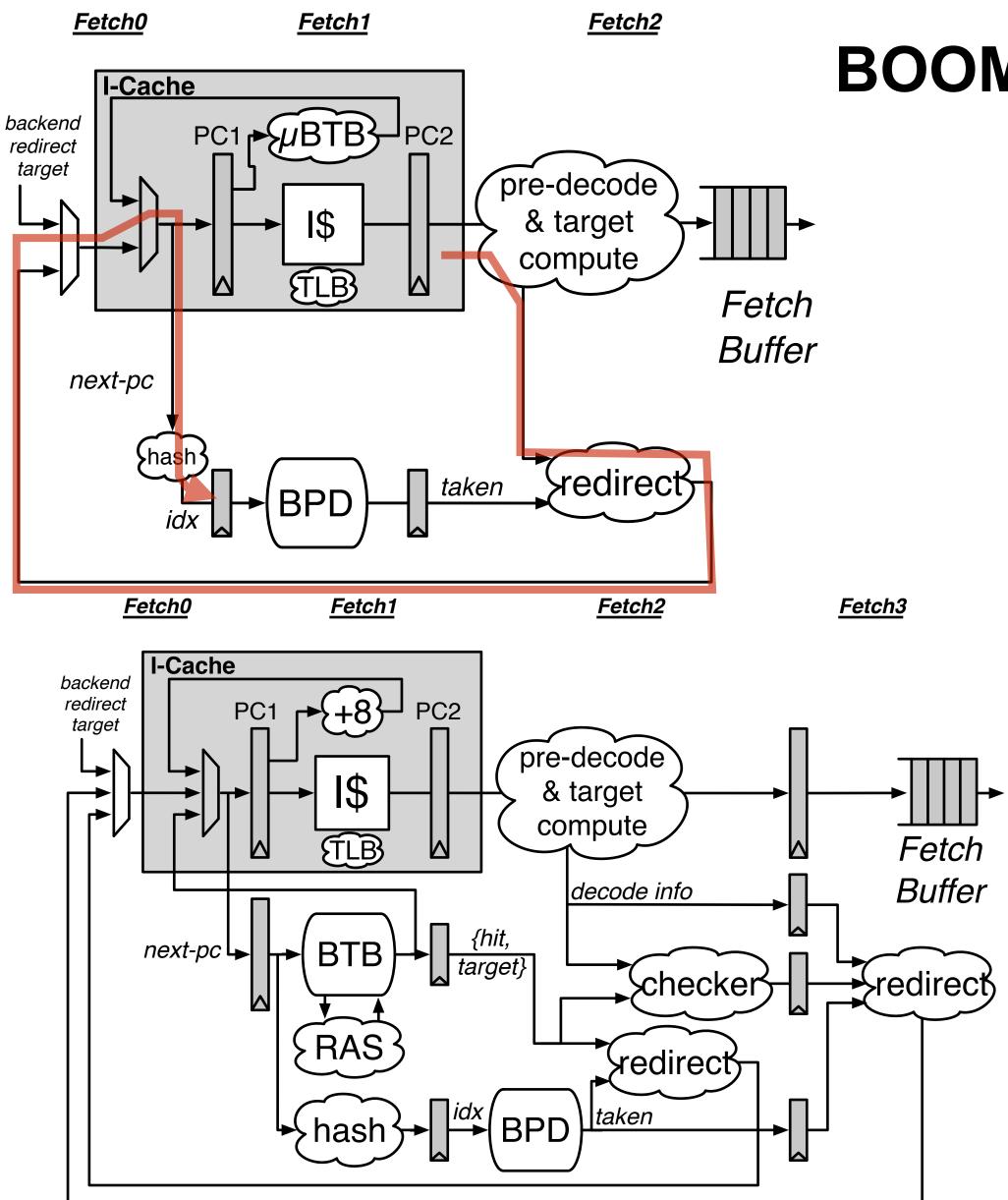












Frontend Design Changes



BOOMv1

- BTB in SRAM
 - -set-associative
 - -partially tagged
 - -Checker to verify integrity
- BPD (Conditional Predictor)
 - -hash gets entire stage
 - -redirect based on BTB
 - -redirect pushed back (I\$)



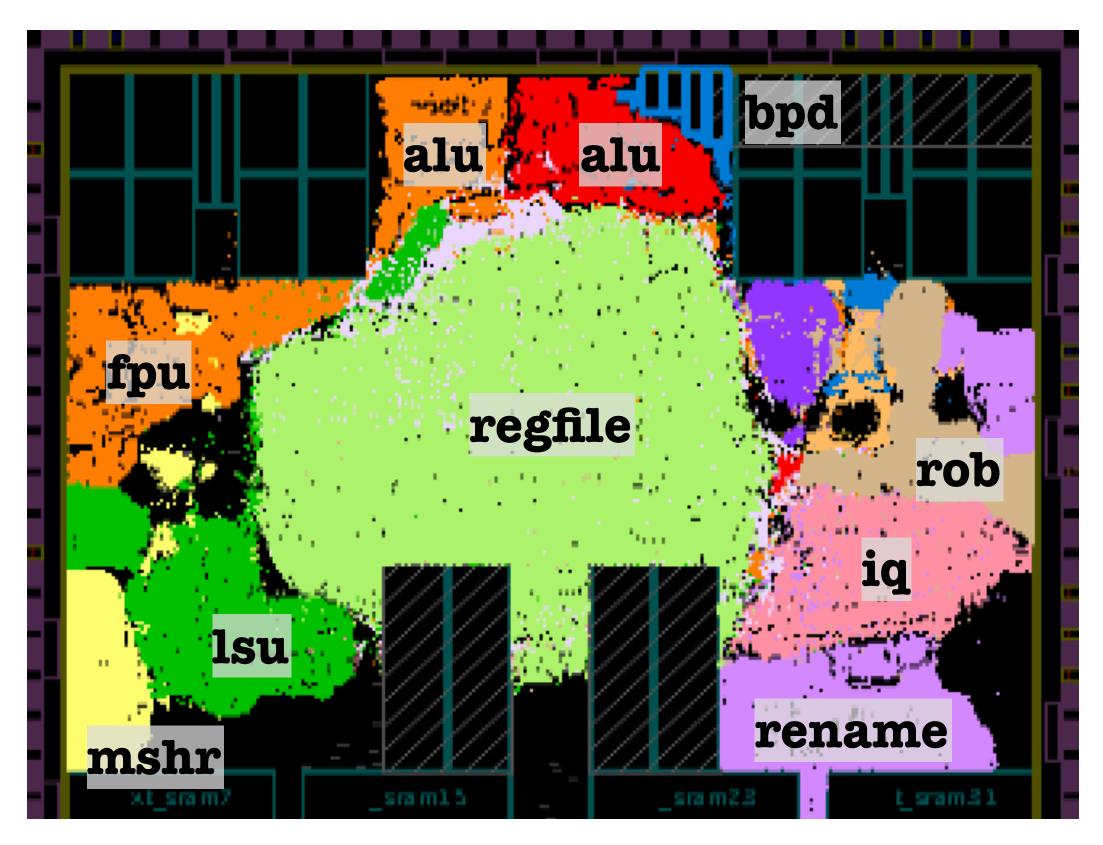




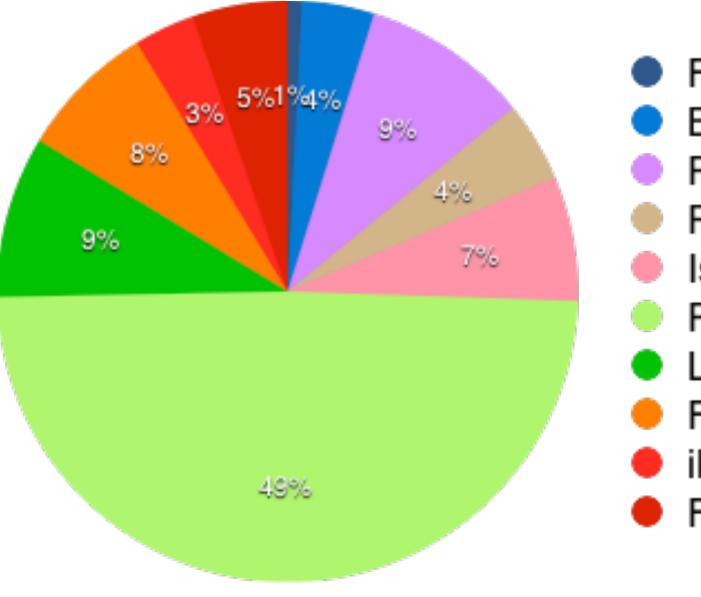


Building a Register File (the first P&R)

BOOMv1 -- 7r3w with 110 registers (INT/FP) Initial Regfile design was infeasible for layout critical paths in issue-select and register read Not DRC/LVS clean



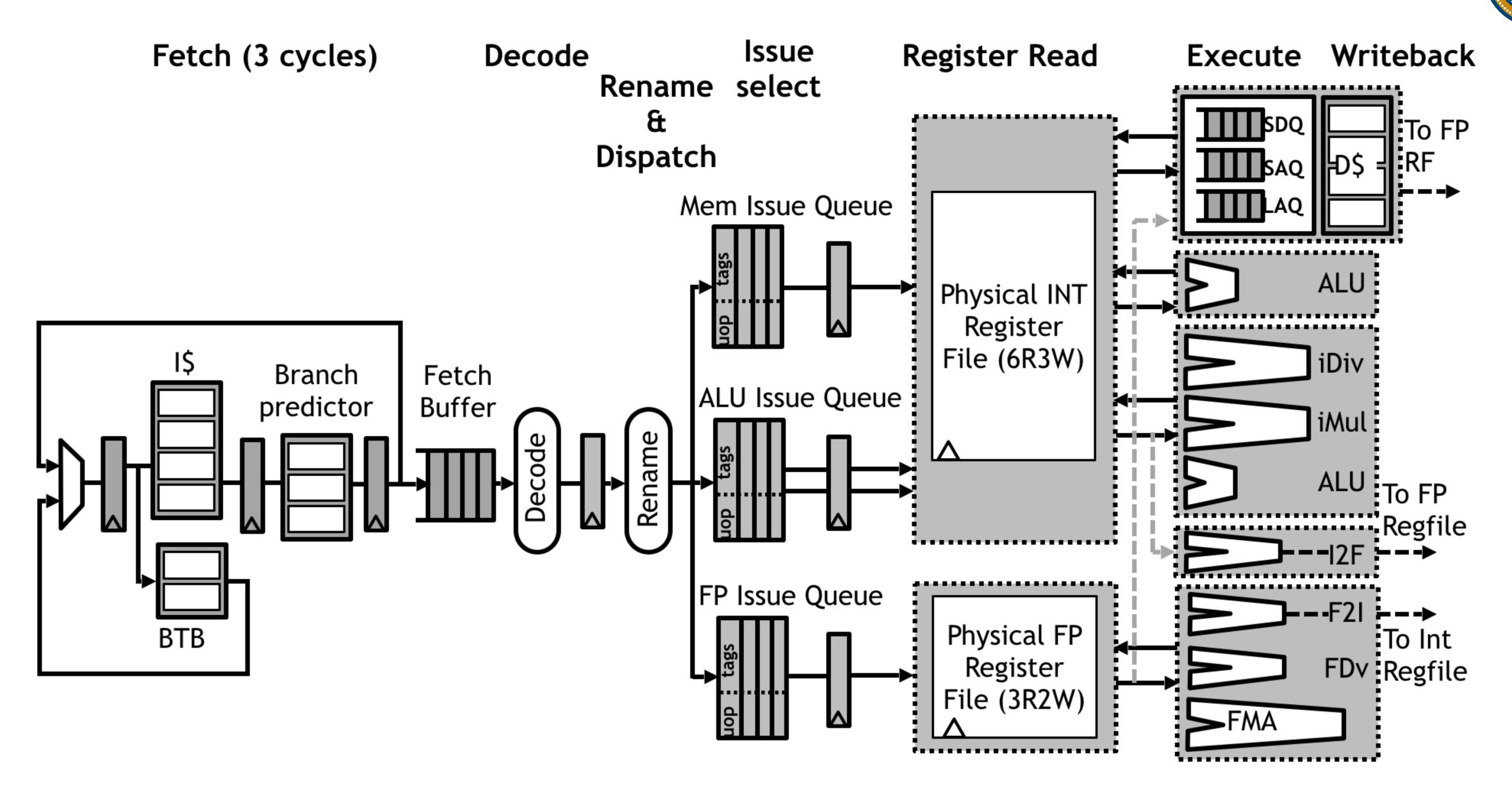








Splitting the Regfile and Issue Queues



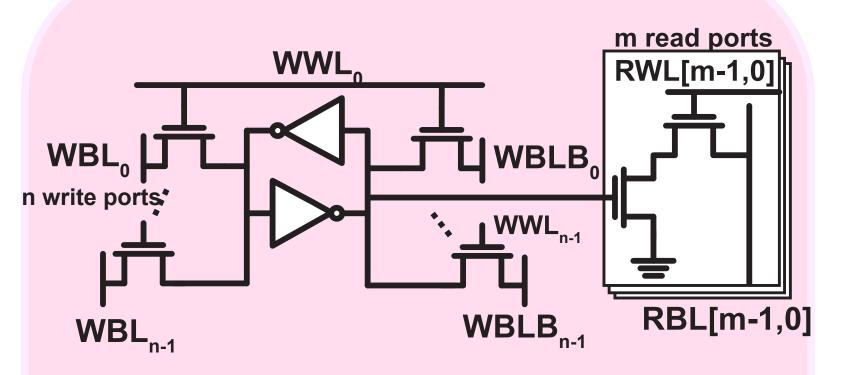


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Multi-port Register File for Design Exploration

Transistor-level



<u>Advantage</u>

- Compact area
- Higher performance

Challenge

- Long design cycle
- Difficult for architecture design exploration

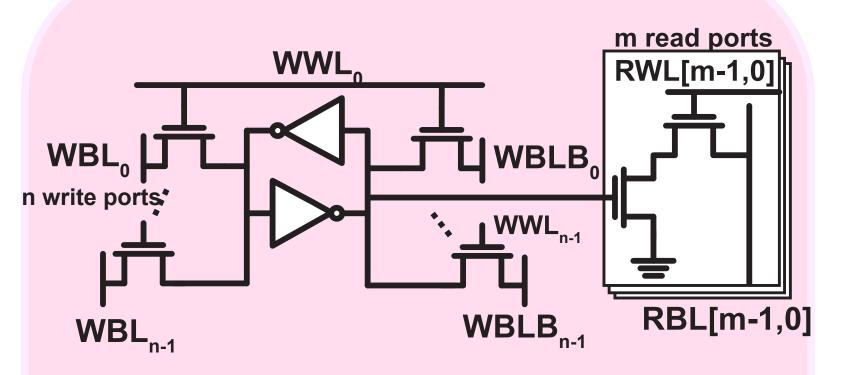


13



Multi-port Register File for Design Exploration

Transistor-level



<u>Advantage</u>

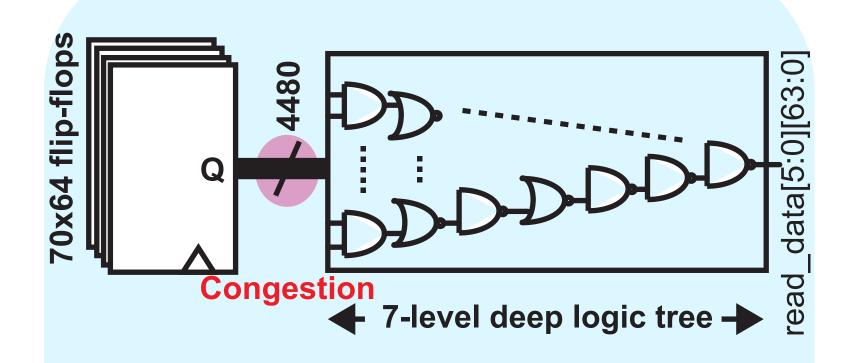
- Compact area
- Higher performance

Challenge

- Long design cycle
- Difficult for architecture design exploration



<u>RTL</u>



<u>Advantage</u>

- Low design effort
- Rapid design exploration

Challenge

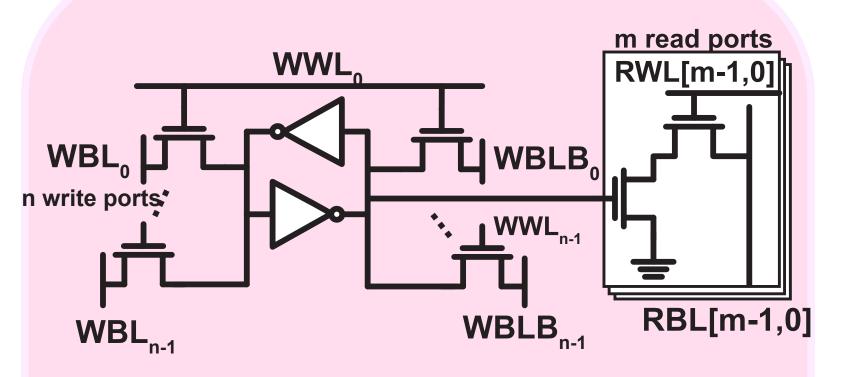
- Large area
- Bad performance
- Routing congestion





Multi-port Register File for Design Exploration

Transistor-level

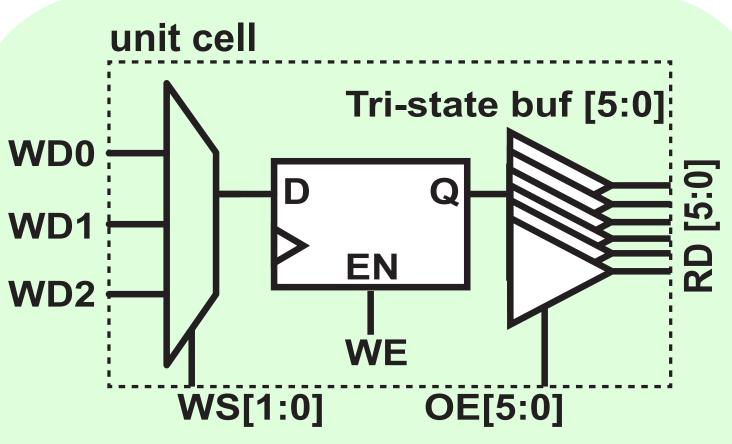


Advantage

- Compact area
- Higher performance lacksquare

Challenge

- Long design cycle
- Difficult for architecture design exploration



Advantage

Challenge

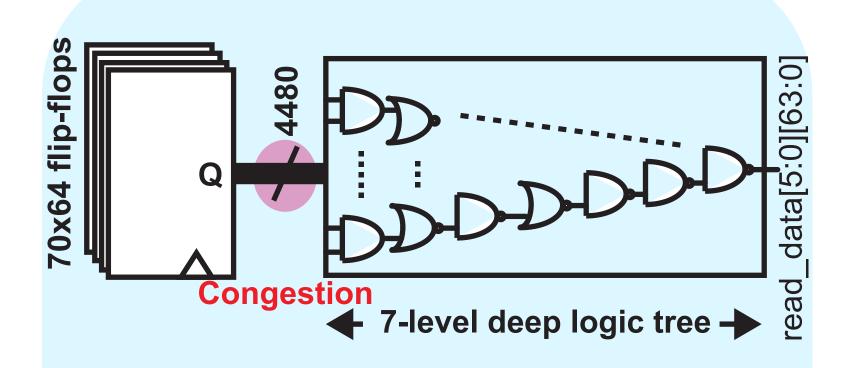
 \bullet optimization



Gate-level

Rapid design exploration Shared read wires solve routing congestion

Guided place-and-route for area/performance



RTL

Advantage

- Low design effort
- Rapid design exploration

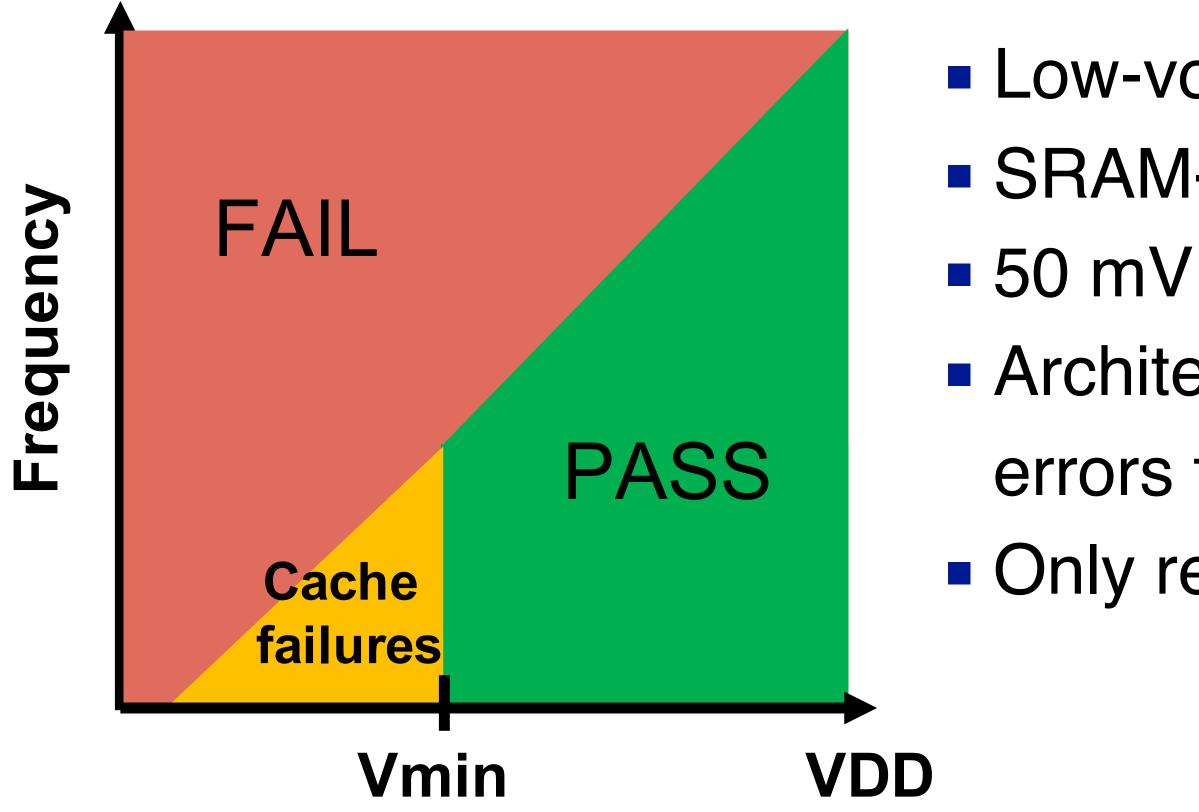
Challenge

- Large area
- Bad performance
- Routing congestion





Resilient Cache for Energy Efficiency





- Low-voltage operation improves energy efficiency
- SRAM-based cache fails at low voltages
- 50 mV reduction in VDD increases BER by 10x
- Architecture-level assist techniques can tolerate
 - errors to reduce Vmin
- Only require RTL changes

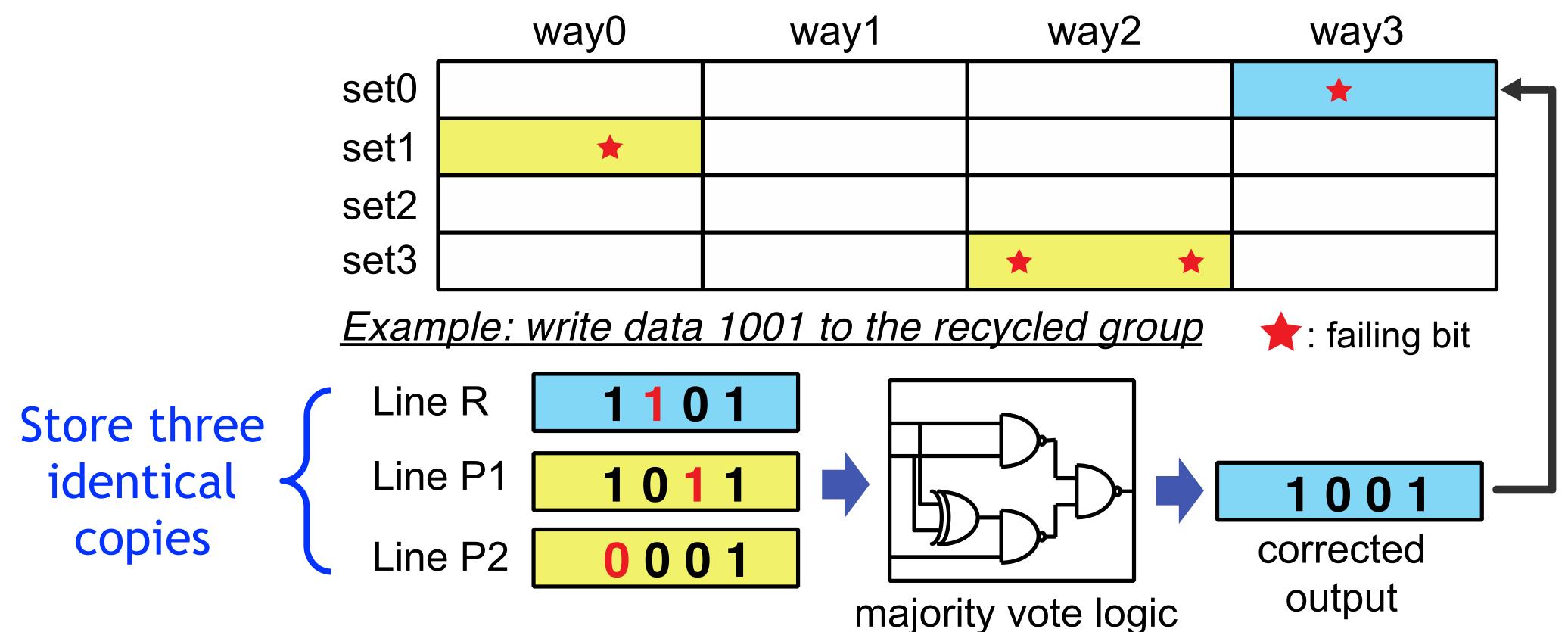












- Group three faulty lines with no error at the same column
- A majority vote of line R/P1/P2 corrects the data output

Line Recycling (LR)

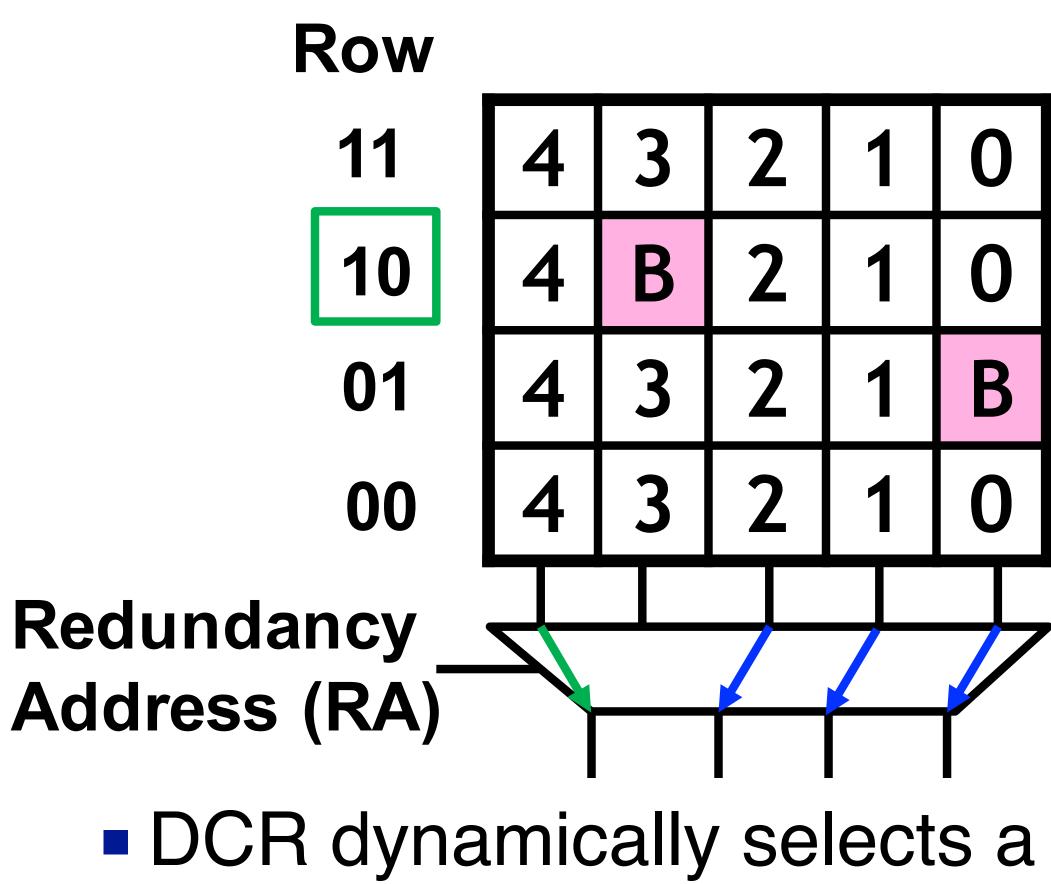


Line Disable (LD) avoids errors by disabling the faulty cache line Two patch lines (line P1/P2) used to repair the recycled line (line R)



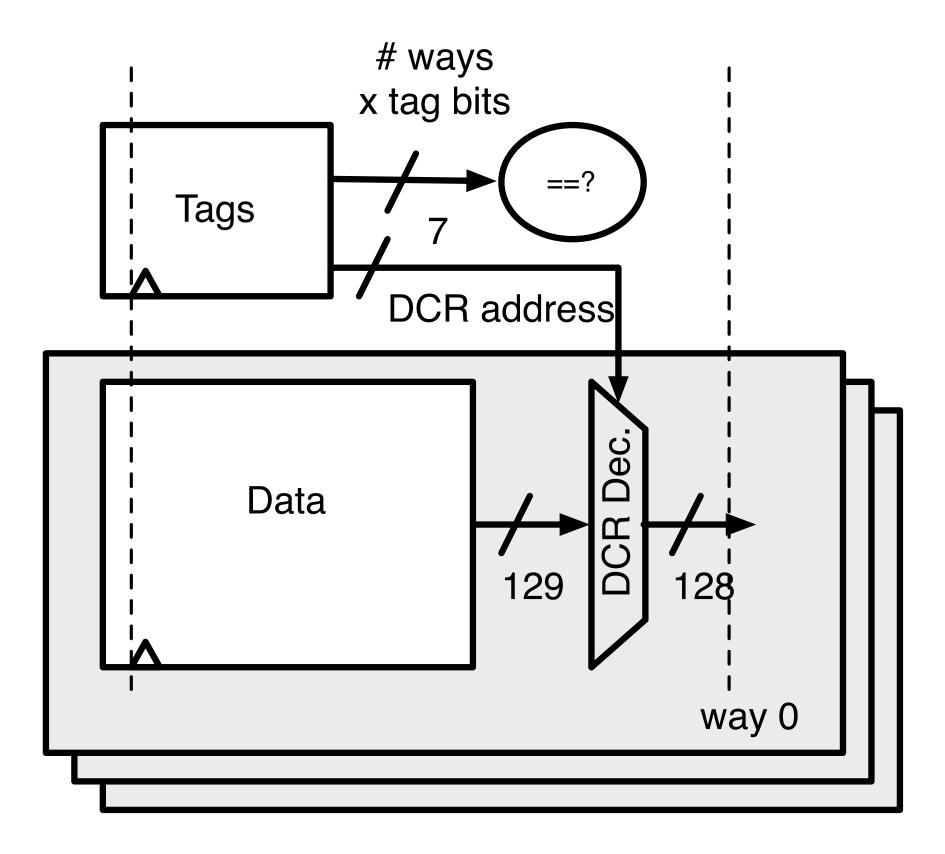


Dynamic Column Redundancy (DCR)



the error according to the redundancy address (RA) Fix 1 bit per set Require LD/LR to handle multi-bit errors





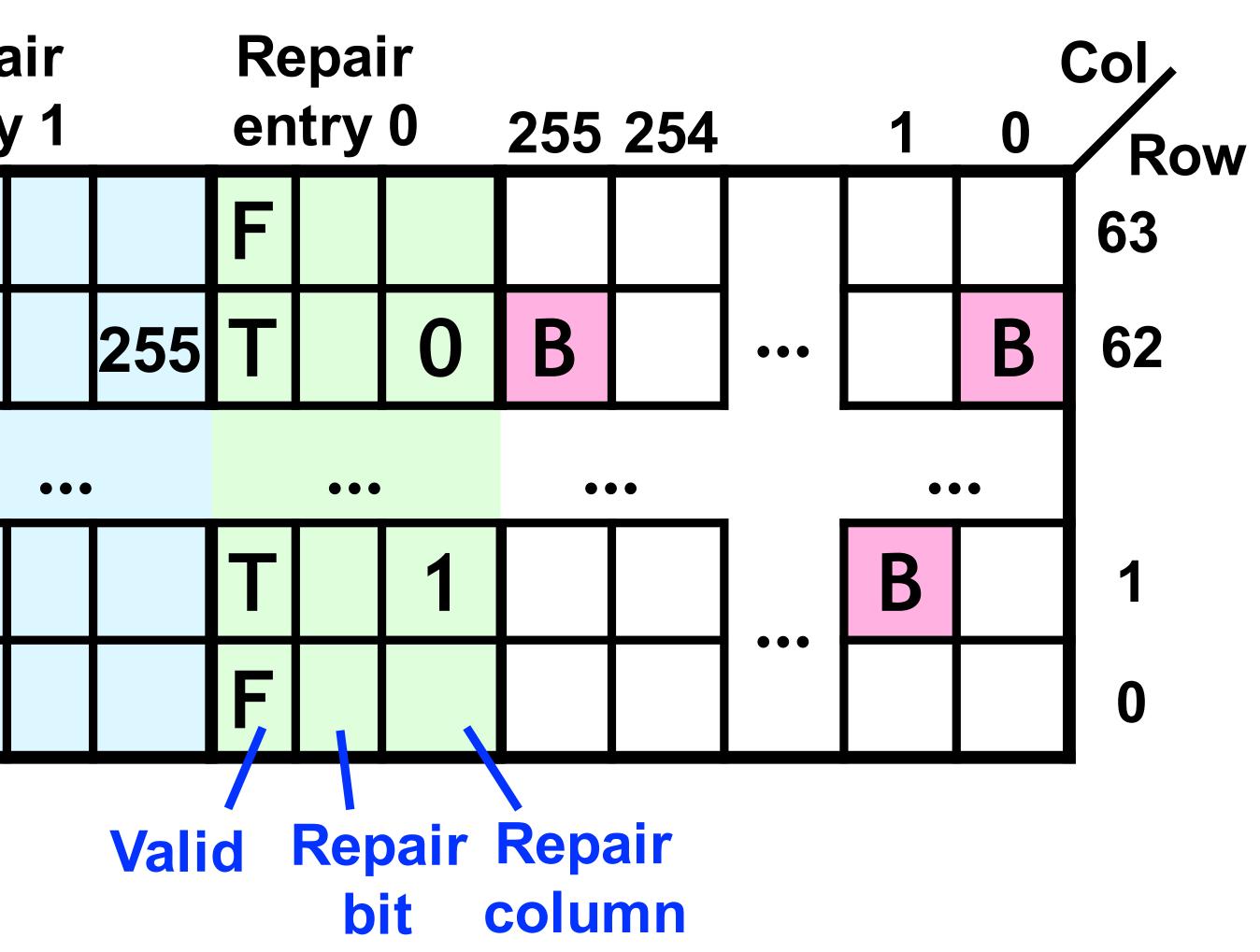
DCR dynamically selects a different multiplexer shift to avoid

16



Bit Bypass with SRAM (BB-S) for tag

Expand tag arrays Repair to store error entries entry 1 Correct more error F with less area -Fix 2 bits per row -An 8T SRAM bitcell is 6x smaller than a flip-flop F -Shared decoder and F peripheral circuit -Area overhead: 8.6% in tag arrays



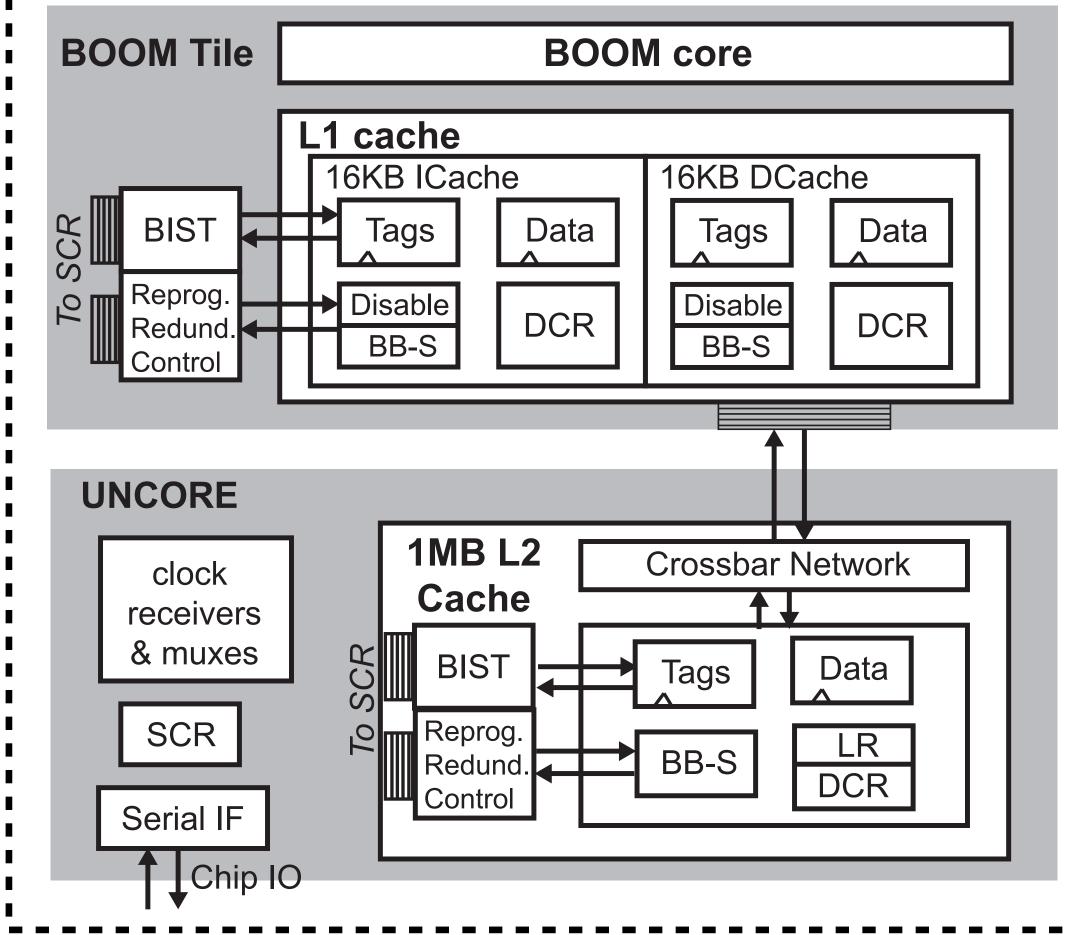






Cache Resiliency Techniques

RocketChip

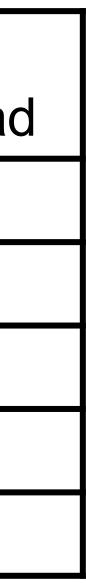




	_		_
Technique	Protected	Timing	Area
	cache	overhead	overhea
LR	L2 data	Small §	0.77%
LD	L1/2 data	Small	0.2%
DCR	L1/2 data	Small	1.1% †
BB-S	L1/2 tag	Small	0.9% †
SECDED	L1/2	Large	10.9% ‡

§Require 3 additional cycles †numbers are reported for L2 ‡1repair/64bit

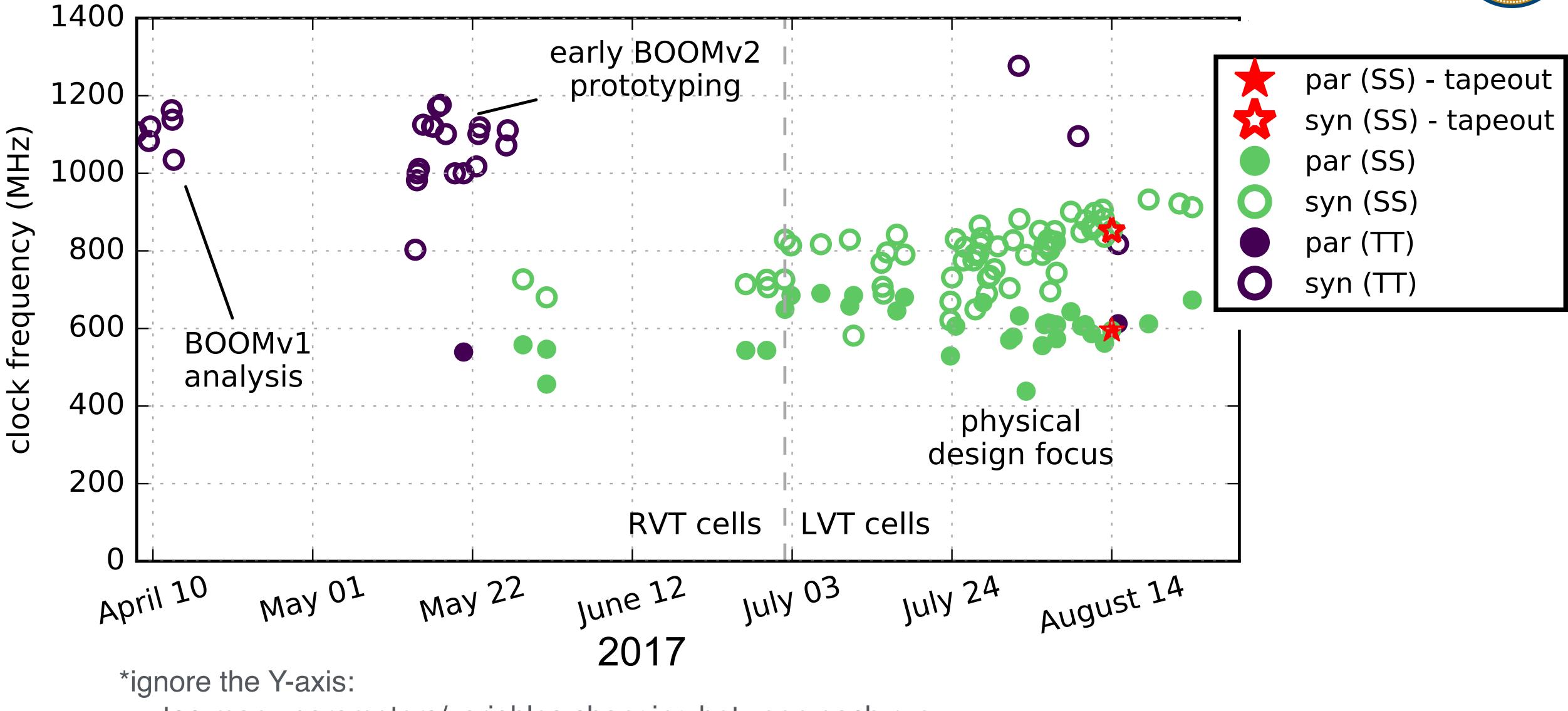
*Data portion is 86.2% of cache area, tag portion is 11% of cache area











-- too many parameters/variables changing between each run

-- doesn't capture DRC violations

4 months of agile tape-out









- RTL hacking can be very agile
 - KHz for Verilator simulator)
- Chisel allows for quick, far-reaching changes - generator approach allows for late-binding design decisions - small changes, improvements (that don't affect floor plan) are agile Physical design is a bottleneck
 - 2-3 hours for synthesis results
 - 8-24 hours for p&r results
 - RTL and PD are tightly coupled
- Verification is a bottleneck
 - I can write bugs faster than I can find them

Agile Hardware Development



-~6 minutes to compile, build, and run "riscv-tests" regression suite (10







Directed tests and a randomized torture generator. Verilator/VCS/FPGA simulation at RTL. VCS for post-gl/par simulation. - Need tests that build up a lot of speculative state. - Need tests that cover OS- and platform-level use-cases. Assertions are king.

Verification

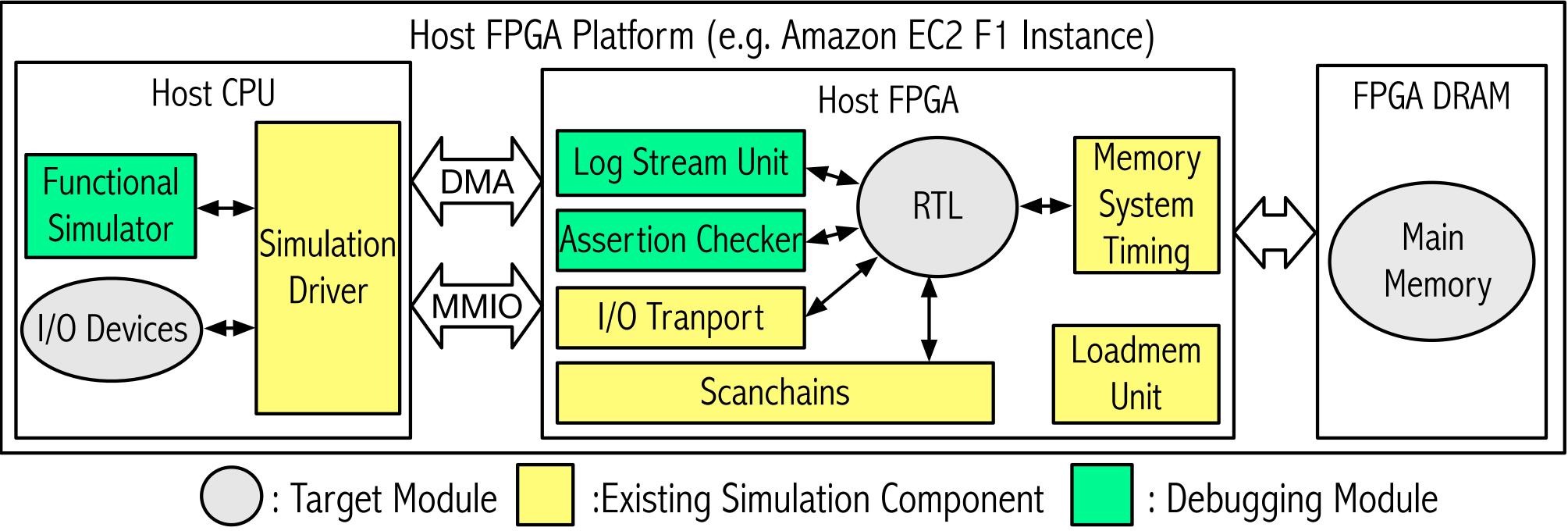


- Speculative OOO pipelines are difficult to get good coverage on.

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DESSERT: Debugging RTL Effectively with State Snapshotting for Error Replays across Trillions of Cycles



- simulation!
- Donggyu Kim, et. al. CARRV 2018
- https://carrv.github.io/2018/papers/CARRV_2018_paper_10.pdf

Co-simulate, find bugs, and get waveforms from Cloud FPGA-based



22



Incorrect Jump Target

401.bzip2 (assertion error at 500 billion cycles)

- JAL jumps to wrong target.
- Due to improper signed arithmetic.
- 2-3 year old bug.
- 3 hours of FPGA time.









Incorrect Jump Target

401.bzip2 (assertion error at 500 billion cycles)

- JAL jumps to wrong target.
- Due to improper signed arithmetic.
- 2-3 year old bug.
- 3 hours of FPGA time.
- Would require 39 years of Verilator simulation to find. - DESSERT found this via a synthesized assertion.



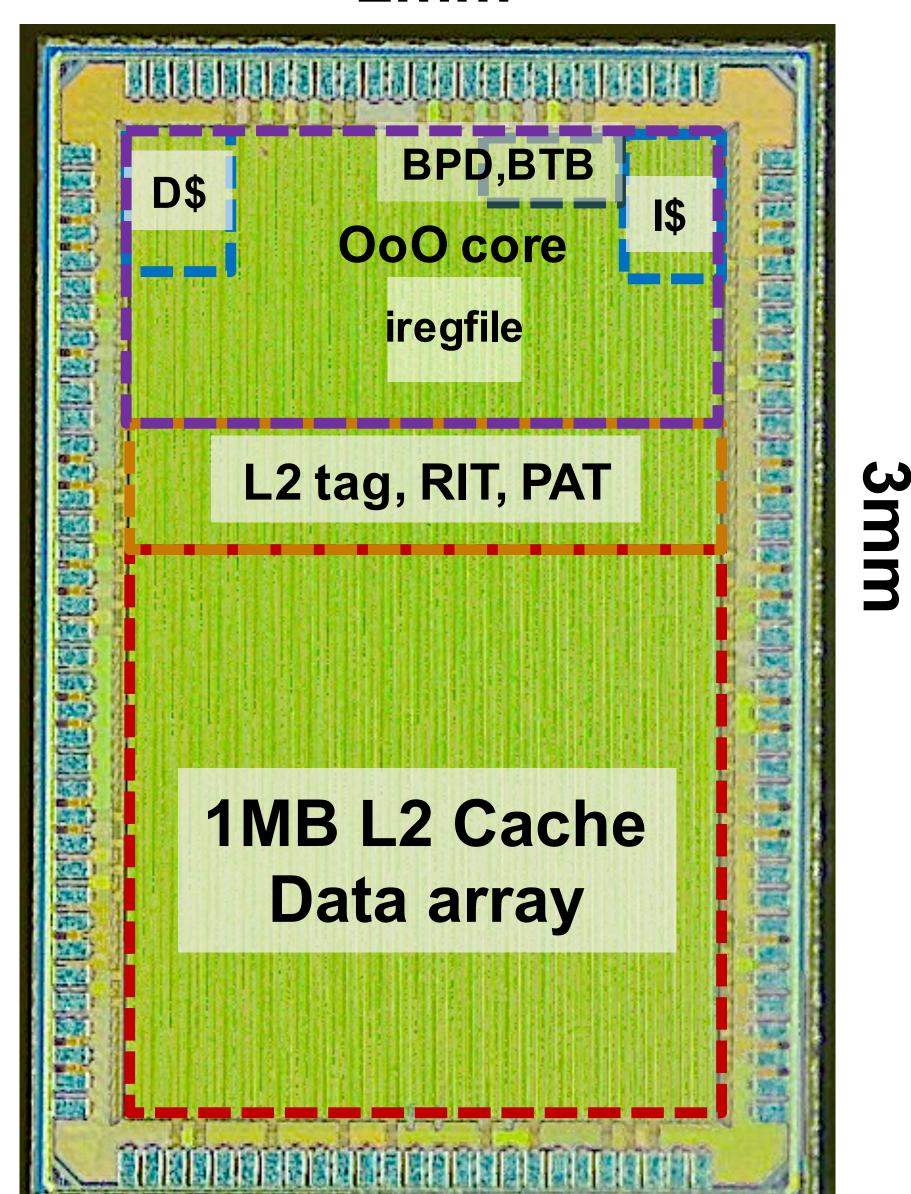




Chip Implementation 2mm

Chip Summary			
ISA	RISC-V RV64IMAFD with Sv39		
Fetch Width	2 insts		
Issue Width	3 micro-ops		
Issue Entries	16 (i) 20 (m) 10 (f)		
Regfile	6R3W (int), 3R2W (fp)		
Exe Units	iALU+iMuI+FMA iALU+fDiv Load/Store		
L1 I/D Cache	4-way, 16KB		
L2 Cache	8-way, 1MB		

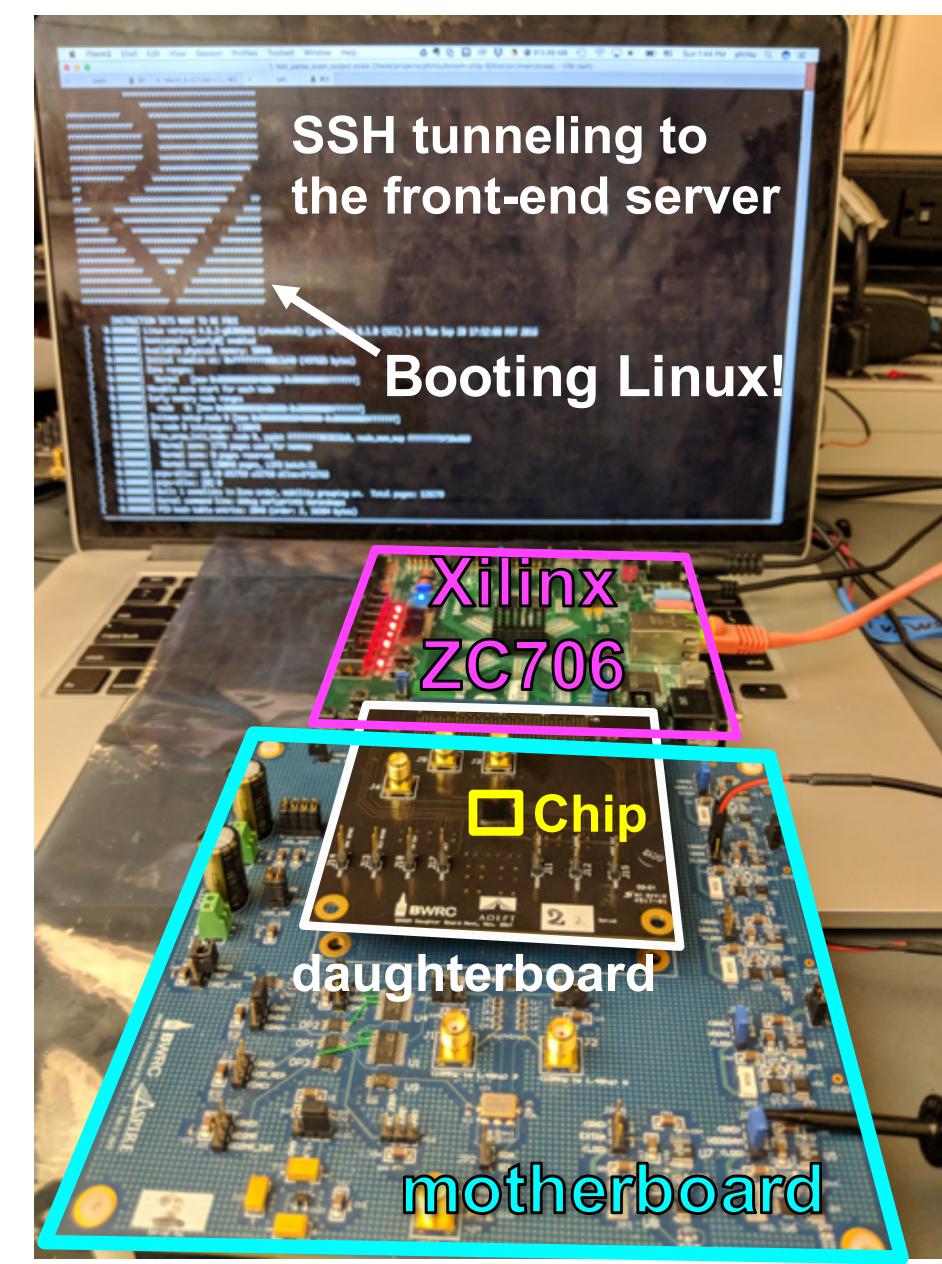




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Experimental Setup



- Chip-on-board (COB) package
- Voltage and clock generation on the motherboard
- Cortex A9 on ZC706 works as the front-end server
- Boot Linux

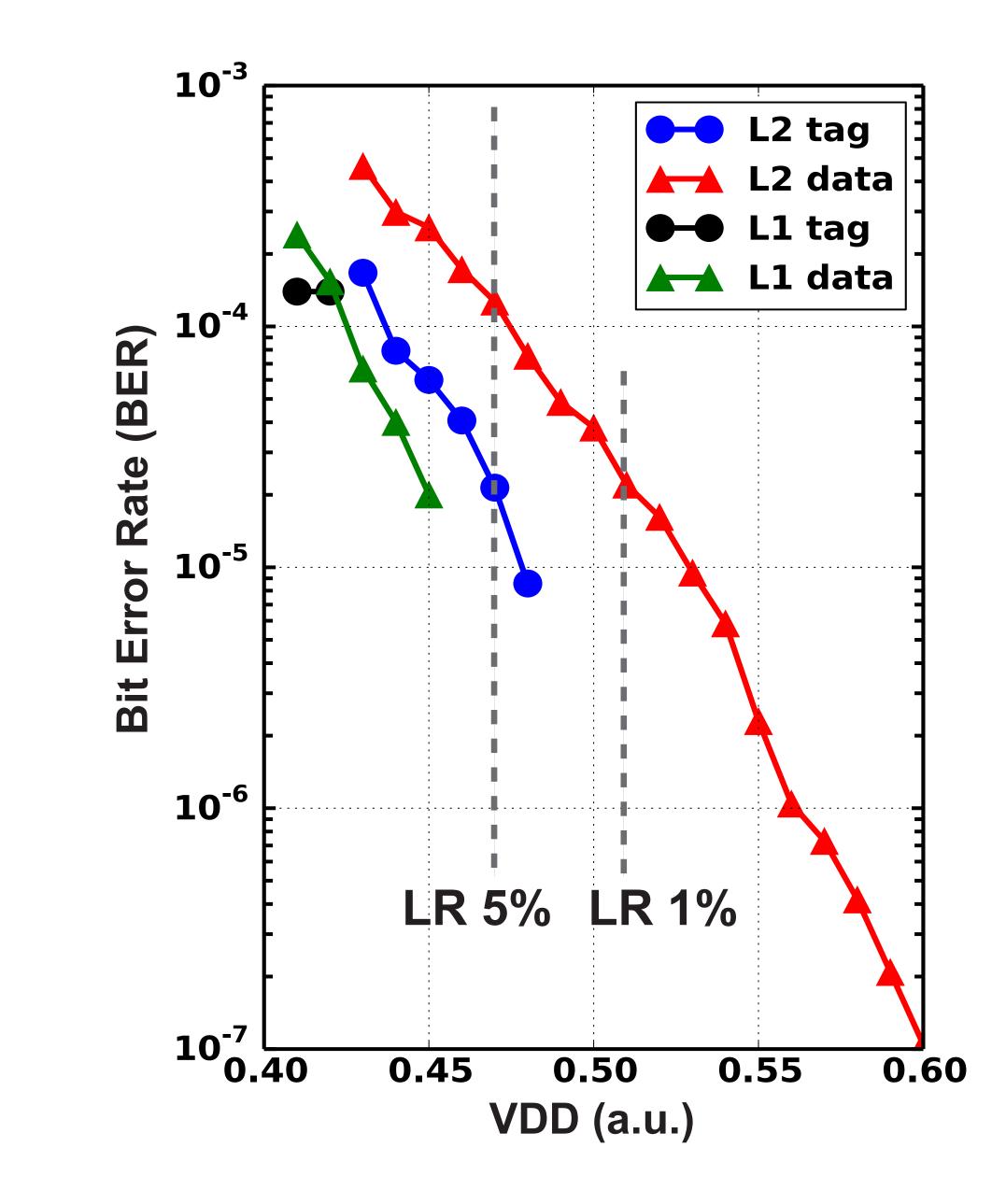
Performance		
Clock frequency	1GHz @0.9V	
	320MHz @0.6V	
Coremark/MHz	3.77	
Instruction Per Cycle	1.11 (@Coremark)	



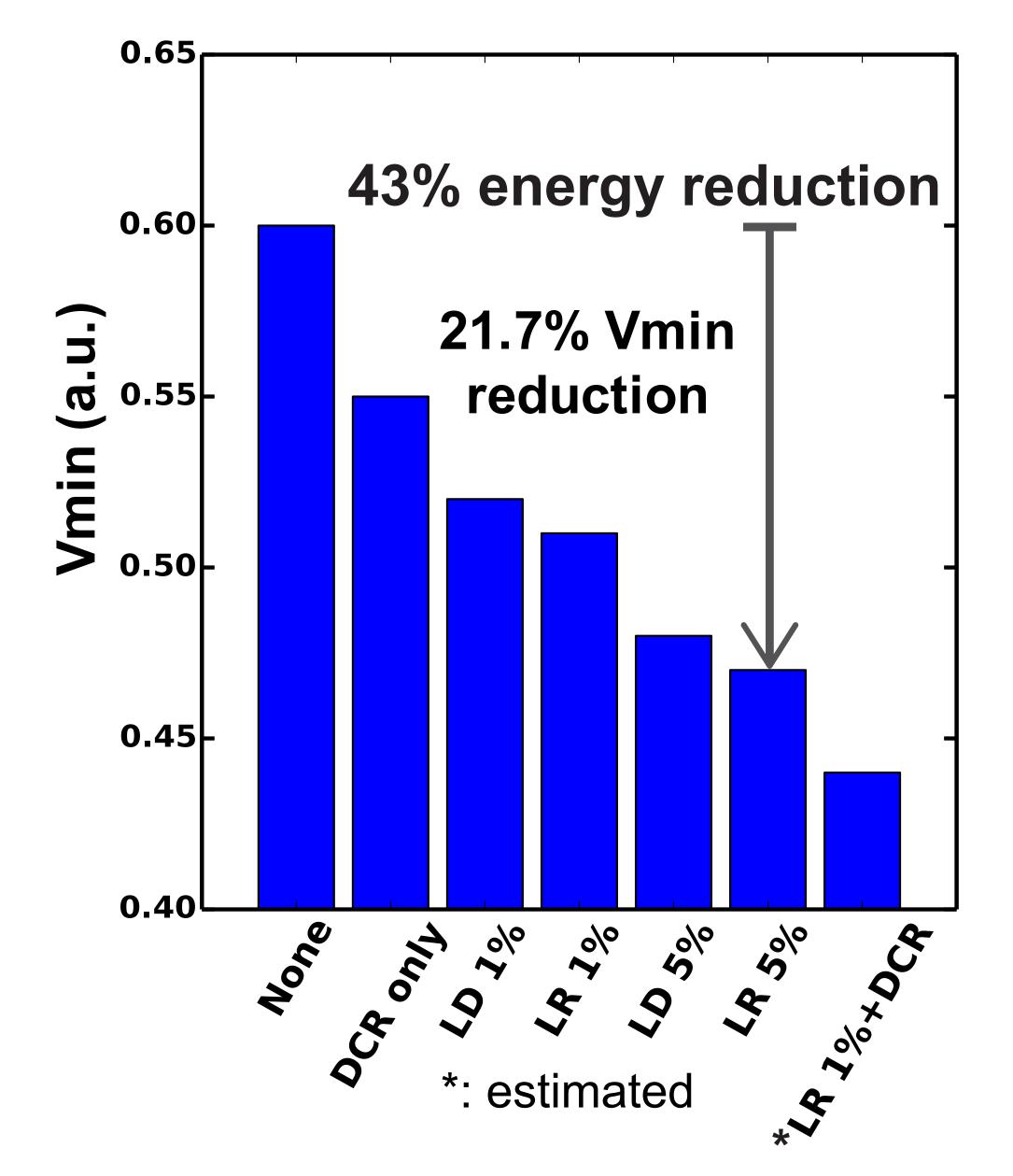




Bit Error Rate and Vmin reduction



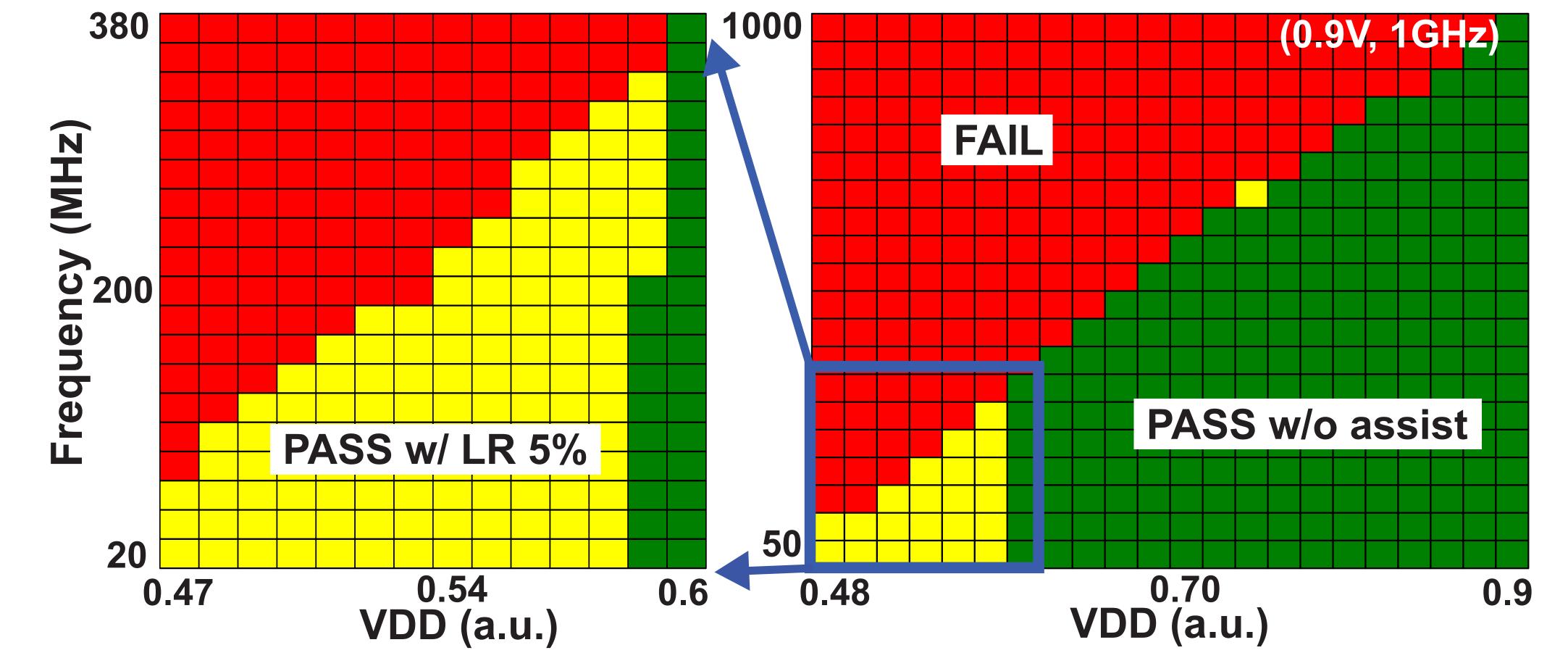








Operating voltage and frequency



With LR and 5% loss of L2 cache capacity, Vmin is reduced to 0.47V@70MHz 2.3% increase in L2 misses, but only 0.2% degradation in IPC



Benchmark: vvadd



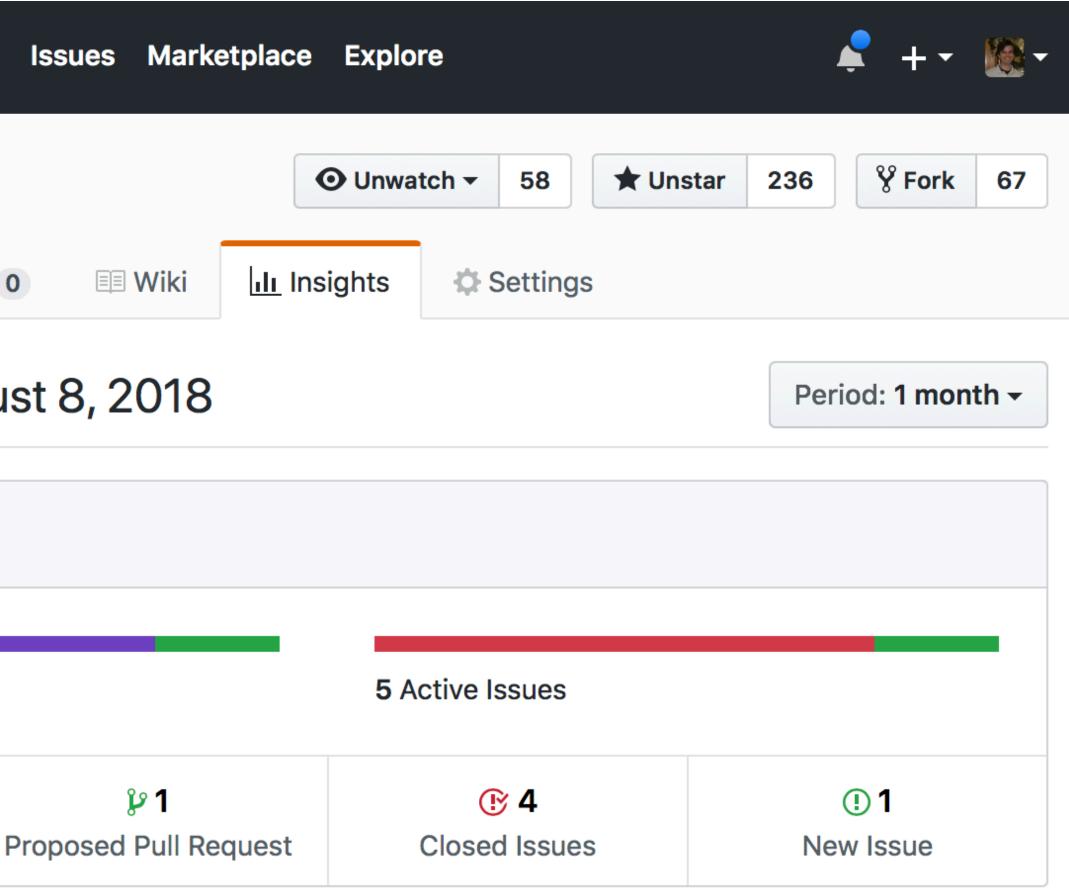




Pi-Feng and Chris have graduated! BOOM will continue to be supported and improved. - github.com/ucb-bar/riscv-boom

Search or jump to	/	Pull reques	ts
📮 ucb-bar / riscv-boom			
<> Code Issues 16	1 Pull requests 4	Project	s C
Pulse	July 8, 20	18 – Auç	gu
Contributors			
Community	Overview		
Traffic			
Commits	5 Active Pul	l Requests	
Code frequency	<u>រ</u> ា 4	L	
Dependency graph	Merged Pull		F

Future Directions















Agile Methodology Research

- How to verify complex IP?
- How do you measure/predict RTL performance, area, power?







SPIRE Lots of opportunities for using the BOOM core

Agile Methodology Research

- How to verify complex IP?
- How do you measure/predict RTL performance, area, power?
- Software Studies
 - Hardware/software co-design.
 - High visibility of very long-running applications.







SPIRE UC Berkelev Lots of opportunities for using the BOOM core Agile Methodology Research

- How to verify complex IP?
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- Software Studies
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 - High visibility of very long-running applications.
- Security Research
 - New class of speculation-based attacks.
 - How to attack?
 - How to defend?
 - Evaluate cost of changes to branch predictors, caches, and more.







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 - How to defend?
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- New RISC-V extensions
 - Variable-length vector.
 - Managed-language support.

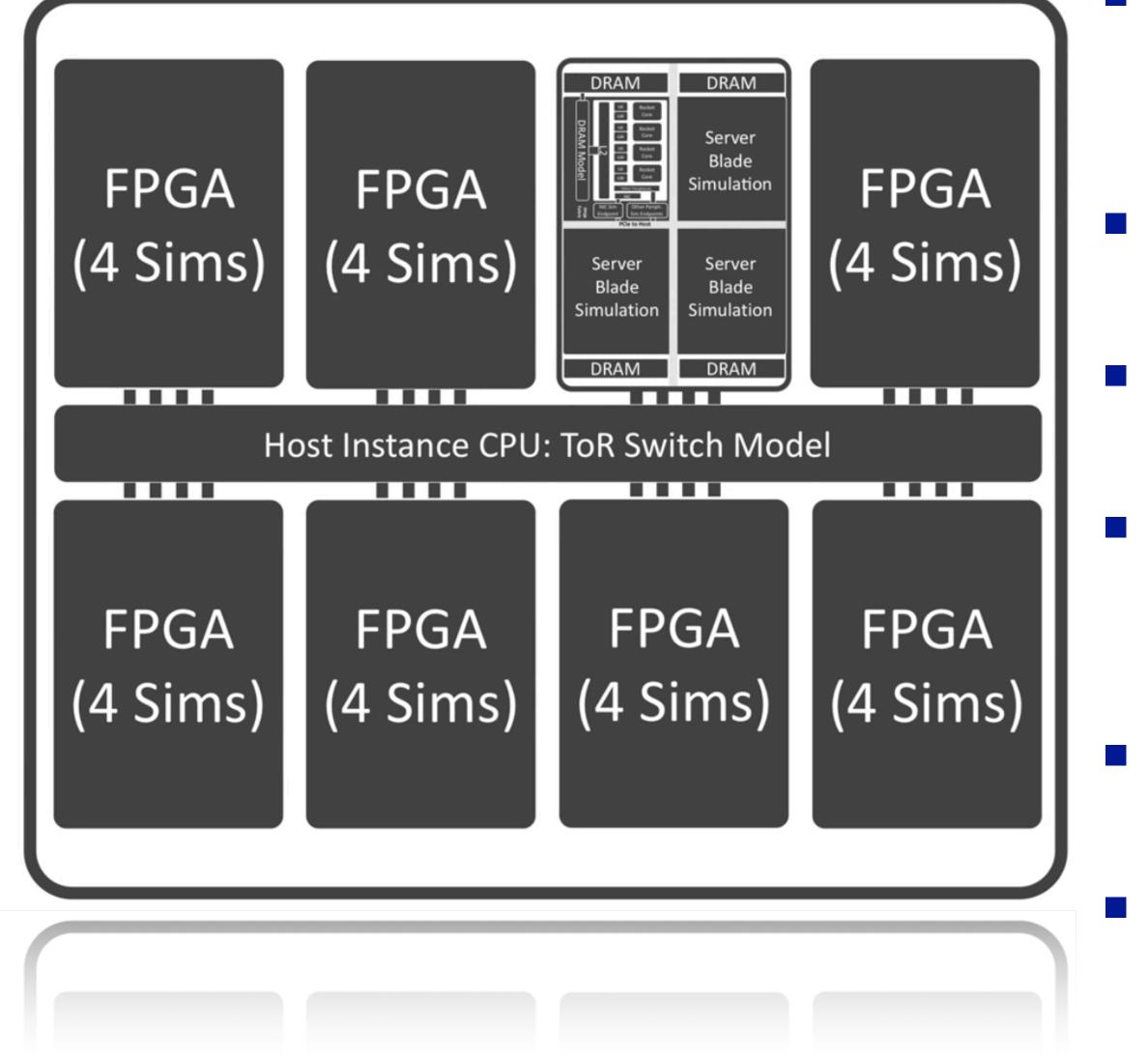






FireSim now supports BOOM!

Shown: a 32 node rack (128 cores)





- FireSim is a open-source cycle-accurate FPGA-accelerated simulation tool that runs on Amazon EC2 F1
- Chisel RTL is automatically transformed into cycle-accurate FPGA simulator
- Peripheral device support:
- -UART, Disk, Ethernet NIC, easy to add more Boot Linux on a multi-core BOOM with
 - 16 GB DDR3, UART, Ethernet NIC in the cloud for 50 cents/hour at ~100 MHz
- FireSim is available at:
 - https://fires.im
- ISCA 2018 Paper:

https://sagark.org/assets/pubs/firesim-isca2018.pdf











A 2-person tapeout takes a village!

RISC-V ISA

- very out-of-order friendly!
- Chisel hardware construction language - object-oriented, functional programming

FIRRTL

- exposed RTL intermediate representation (IR)
- Rocket-chip
 - A full working SoC platform built around the Rocket in-order core
- Thanks to:
 - Rimas Avizienis, Jonathan Bachrach, Scott Beamer, David Biancolin, Henry Cook, Palmer Dabbelt, John Hauser, Adam Izraelevitz, Sagar Karandikar, Ben Keller, Donggyu Kim, Jack Koenig, Jim Lawson, Yunsup Lee, Richard Lin, Eric Love, Martin Maas, Chick Markley, Albert Magyar, Howard Mao, Miquel Moreto, Quan Nguyen, Albert Ou, Brian Richards, Colin Schmidt, Wenyu Tang, Stephen Twigg, Huy Vo, Andrew Waterman, Angie Wang, Jerry Zhao, and more...



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- does not necessarily reflect the position or the policy of the sponsors.

Thank you!



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